

# FDB3502

## N-Channel Power Trench® MOSFET 75V, 14A, 47mΩ

### Features

- Max  $r_{DS(on)}$  = 47mΩ at  $V_{GS} = 10V$ ,  $I_D = 6A$
- 100% UIL Tested
- RoHS Compliant

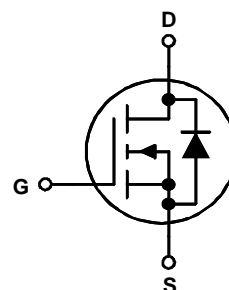
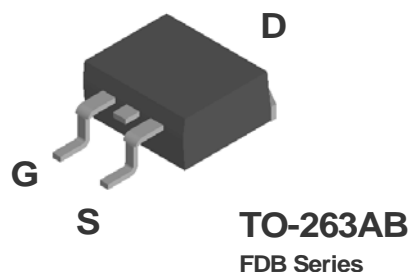


### General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Application

- Synchronous rectifier



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	75	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current -Continuous (Package limited) $T_C = 25^\circ\text{C}$	14	A
	-Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	22	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	6	
	-Pulsed	40	
$E_{AS}$	Single Pulse Avalanche Energy (Note 3)	54	mJ
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	41	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	3.1	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	3	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	40	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB3502	FDB3502	TO-263AB	330 mm	24 mm	800 units

**Electrical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off Characteristics**

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$	75			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , referenced to $25^\circ\text{C}$		70		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{V}$ , $V_{DS} = 60\text{V}$ ,			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}$ , $V_{DS} = 0\text{V}$			$\pm 100$	nA

**On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$	2.5	3.8	4.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , referenced to $25^\circ\text{C}$		-10		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}$ , $I_D = 6\text{A}$		37	47	m $\Omega$
		$V_{GS} = 10\text{V}$ , $I_D = 6\text{A}$ , $T_J = 125^\circ\text{C}$		63	80	
$g_{FS}$	Forward Transconductance	$V_{DD} = 10\text{V}$ , $I_D = 6\text{A}$		13		S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 40\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$		615	815	pF
$C_{oss}$	Output Capacitance			75	105	pF
$C_{rss}$	Reverse Transfer Capacitance			35	40	pF
$R_g$	Gate Resistance	$f = 1\text{MHz}$		1.5		$\Omega$

**Switching Characteristics**

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 40\text{V}$ , $I_D = 6\text{A}$ , $V_{GS} = 10\text{V}$ , $R_{GEN} = 6\Omega$		9	17	ns
$t_r$	Rise Time			3	10	ns
$t_{d(off)}$	Turn-Off Delay Time			13	22	ns
$t_f$	Fall Time			3	10	ns
$Q_g$	Total Gate Charge at 10V	$V_{DD} = 40\text{V}$ , $I_D = 6\text{A}$		11	15	nC
$Q_{gs}$	Gate to Source Charge			4		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			3		nC

**Drain-Source Diode Characteristics**

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}$ , $I_S = 2.6\text{A}$ (Note 2)		0.78	1.2	V
		$V_{GS} = 0\text{V}$ , $I_S = 6\text{A}$ (Note 2)		0.83	1.3	
$t_{rr}$	Reverse Recovery Time	$I_F = 6\text{A}$ , $di/dt = 100\text{A}/\mu\text{s}$		25	41	ns
$Q_{rr}$	Reverse Recovery Charge			17	32	nC

**Notes:**

1:  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design.

- a.  $40^\circ\text{C/W}$  when mounted on a  $1\text{ in}^2$  pad of 2 oz copper
- b.  $62.5^\circ\text{C/W}$  when mounted on a minimum pad.

2: Pulse Test: Pulse Width  $< 300\mu\text{s}$ , Duty cycle  $< 2.0\%$ .

3: Starting  $T_J = 25^\circ\text{C}$ ,  $L = 3\text{mH}$ ,  $I_{AS} = 6\text{A}$ ,  $V_{DD} = 75\text{V}$ ,  $V_{GS} = 10\text{V}$ .

## Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

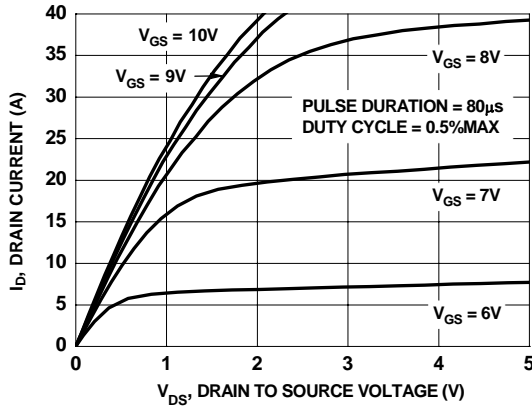


Figure 1. On-Region Characteristics

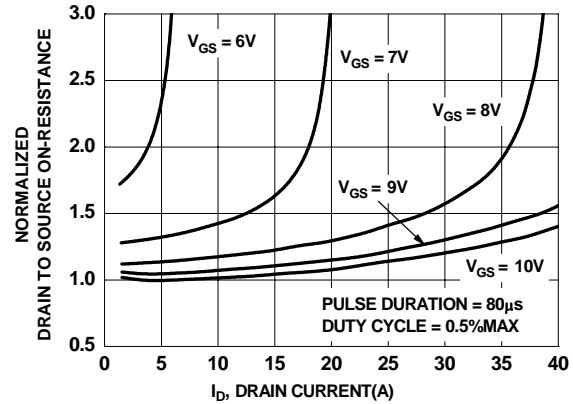


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

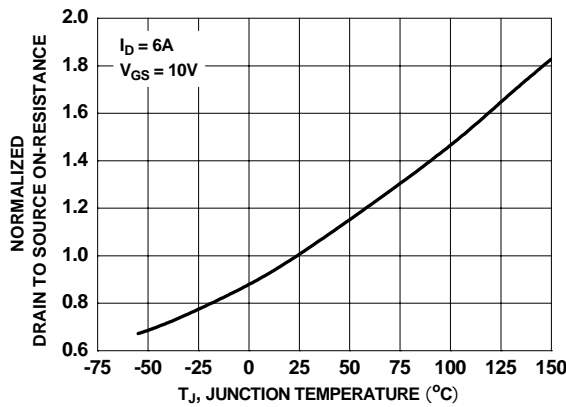


Figure 3. Normalized On-Resistance vs Junction Temperature

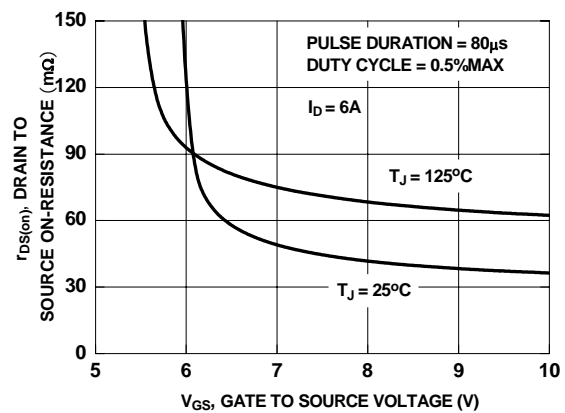


Figure 4. On-Resistance vs Gate to Source Voltage

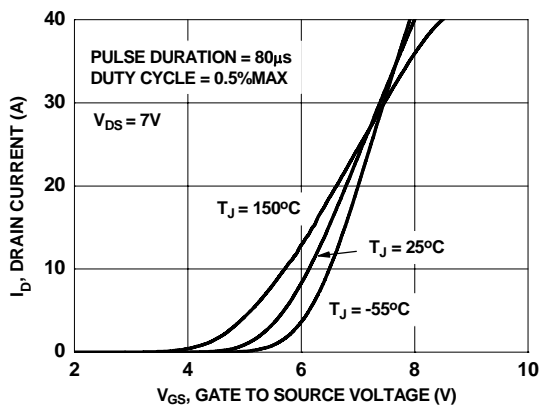


Figure 5. Transfer Characteristics

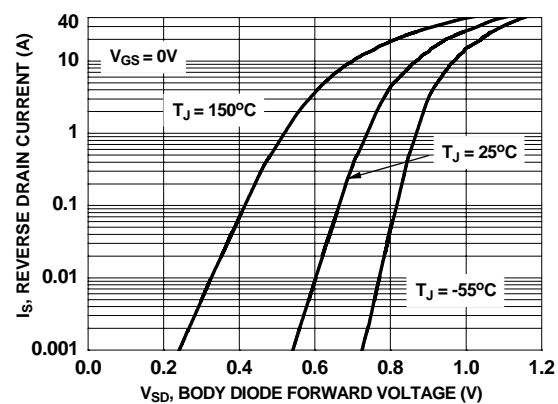


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

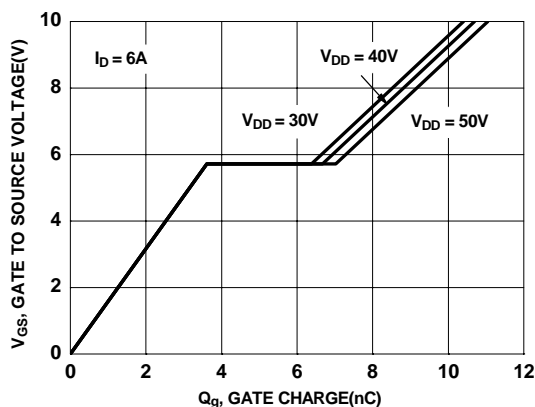


Figure 7. Gate Charge Characteristics

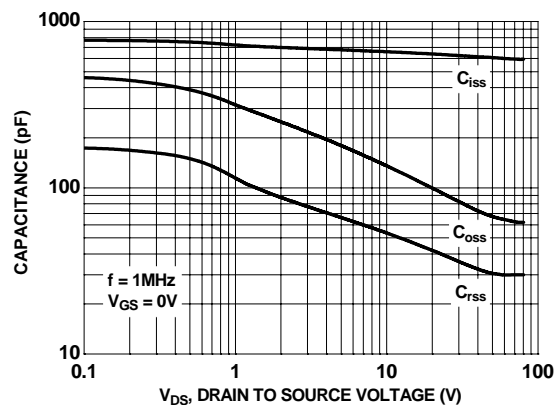


Figure 8. Capacitance vs Drain to Source Voltage

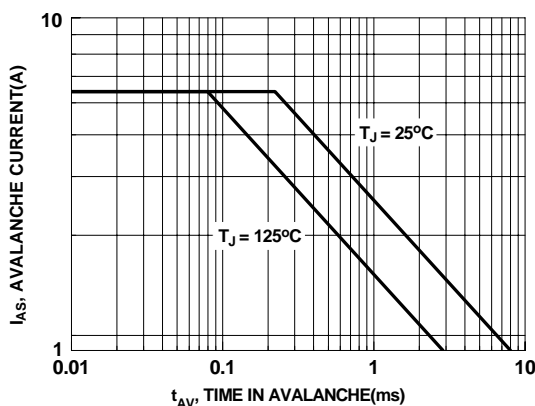


Figure 9. Unclamped Inductive Switching Capability

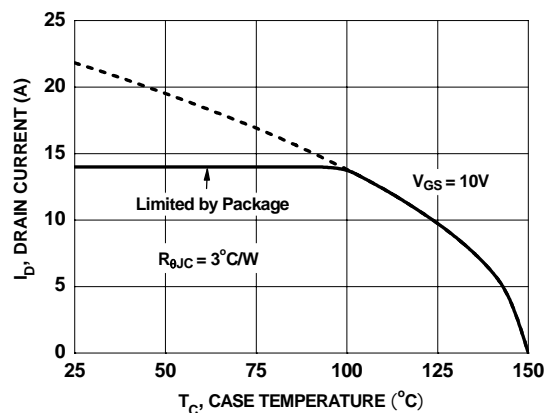


Figure 10. Maximum Continuous Drain Current vs Case Temperature

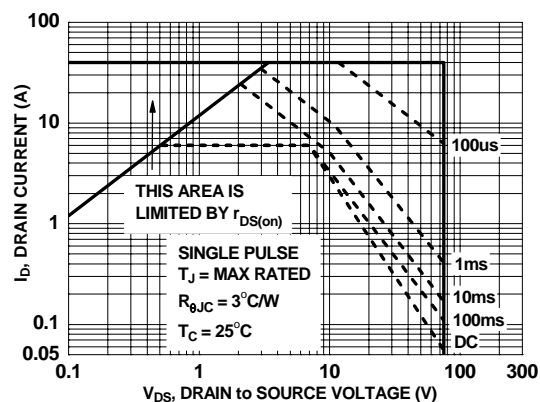


Figure 11. Forward Bias Safe Operating Area

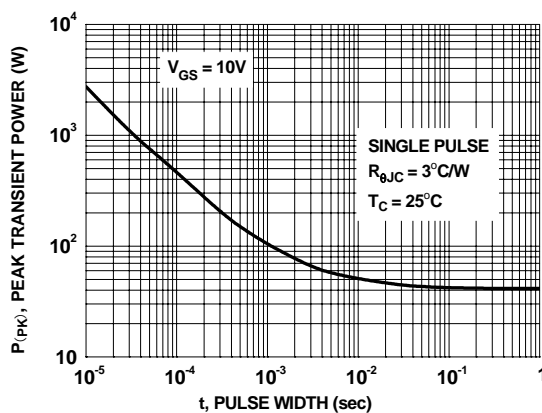
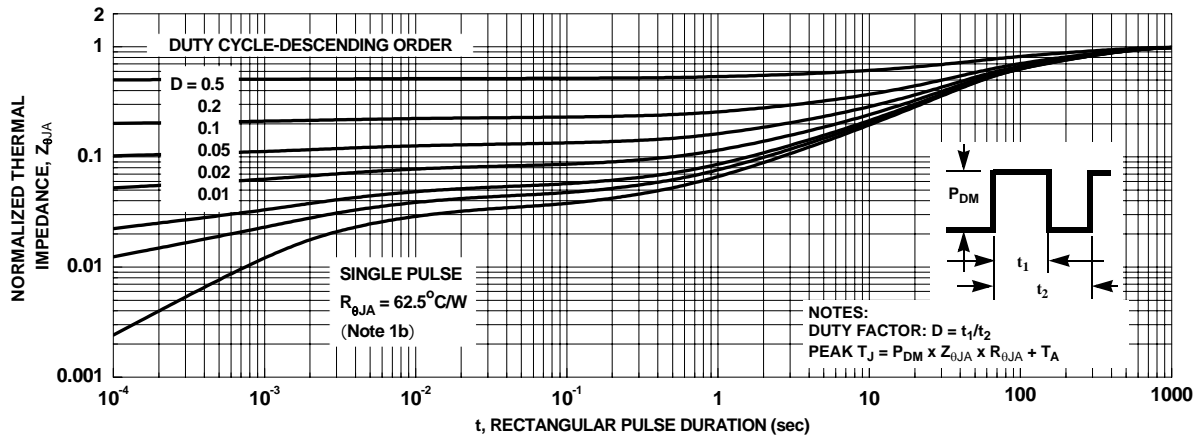
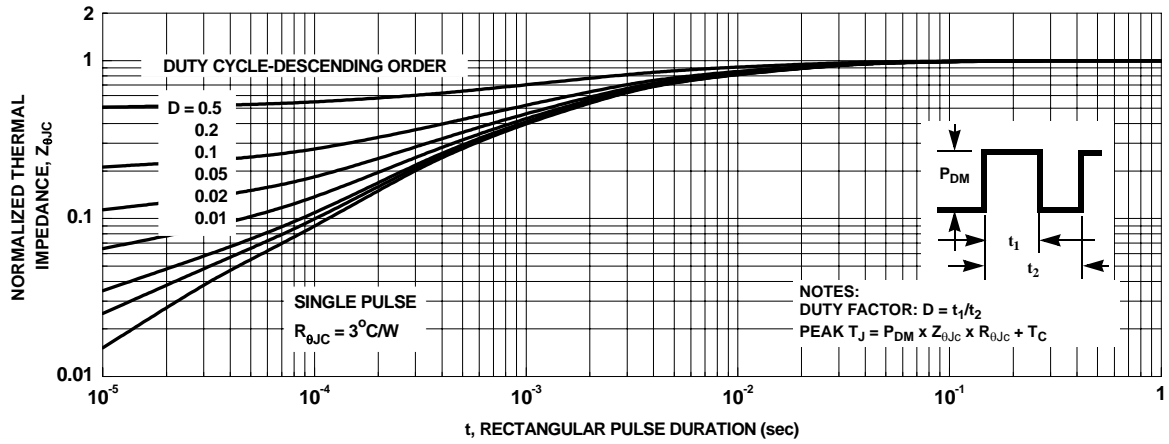


Figure 12. Single Pulse Maximum Power Dissipation



**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted





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